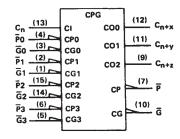
Directly Compatible for Use With: SN54LS181/SN74LS181, SN54S281/SN74S281, SN54S381, SN74S381, SN54S481/SN74S481

PIN DESIGNATIONS

ALTERNATIVE	DESIGNATIONS†	PIN NOS.	FUNCTION
G0, G1, G2, G3	G0, G1, G2, G3	3, 1, 14, 5	CARRY GENERATE INPUTS
P0, P1, P2, P3	P0, P1, P2, P3	4, 2, 15, 6	CARRY PROPAGATE INPUTS
Cn	C _n	13	CARRY INPUT
C _{n+x} , C _{n+y} , C _{n+z}	$\overline{C}_{n+x}, \overline{C}_{n+y}, \overline{C}_{n+z}$	12, 11, 9	CARRY OUTPUTS
Ğ	Y	10	CARRY GENERATE OUTPUT
P	×	7	CARRY PROPAGATE OUTPUT
V	'cc	16	SUPPLY VOLTAGE
G	IND	8	GROUND

 $[\]ensuremath{^{\dagger}}$ Interpretations are illustrated in the 'LS181, 'S181 data sheet.

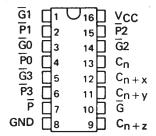
logic symbol‡



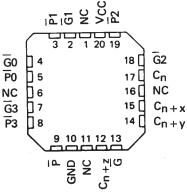
[‡]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54S182 . . . J OR W PACKAGE SN74S182 . . . D OR N PACKAGE (TOP VIEW)



SN54S182 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description

The SN54S182 and SN74S182 are high-speed, look-ahead carry generators capable of anticipating a carry across four binary adders or group of adders. They are cascadable to perform full look-ahead across n-bit adders. Carry, generate-carry, and propagate-carry functions are provided as enumerated in the pin designation table above.

When used in conjunction with the 'LS181 or 'S181 arithmetic logic unit (ALU), these generators provide high-speed carry look-ahead capability for any word length. Each 'S182 generates the look-ahead (anticipated carry) across a group of four ALUs and, in addition, other carry look-ahead circuits may be employed to anticipate carry across sections of four look-ahead packages up to n-bits. The method of cascading 'S182 circuits to perform multilevel look-ahead is illustrated under typical application data.

The carry functions (inputs, outputs, generate, and propagate) of the look-ahead generators are implemented in the compatible forms for direct connection to the ALU. Reinterpretations of carry functions as explained on the 'LS181 and 'S181 data sheet are also applicable to and compatible with the look-ahead generator. Logic equations for the 'S182 are:

$$\begin{array}{lll} C_{n+x} = G0 + P0 \ C_{n} & \overline{C}_{n+x} = \overline{Y0 \ (X0 + C_{n})} \\ C_{n+y} = G1 + P1 \ G0 + P1 \ P0 \ C_{n} & \overline{C}_{n+y} = \overline{Y1 \ [X1 + Y0 \ (X0 + C_{n})]} \\ C_{n+z} = G2 + P2 \ G1 + P2 \ P1 \ G0 + P2 \ P1 \ P0 \ C_{n} & \overline{C}_{n+z} = \overline{Y2 \ (X2 + Y1 \ [X1 + Y0 \ (X0 + C_{n})])} \\ \overline{C}_{n+z} = \overline{Y2 \ (X3 + Y2) \ (X3 + X2 + Y1) \ (X3 + X2 + X1 + Y0)} \\ \overline{C}_{n+z} = \overline{Y3 \ (X3 + Y2) \ (X3 + X2 + Y1) \ (X3 + X2 + X1 + Y0)} \\ \overline{C}_{n+z} = \overline{Y3 \ (X3 + Y2) \ (X3 + X2 + Y1) \ (X3 + X2 + X1 + Y0)} \\ \overline{C}_{n+z} = \overline{Y0 \ (X0 + C_{n})} \\ \overline{C}_{n+z} = \overline{Y0 \ (X0 + C_{n})} \\ \overline{C}_{n+z} = \overline{Y2 \ (X3 + Y2) \ (X3 + X2 + Y1) \ (X3 + X2 + X1 + Y0)} \\ \overline{C}_{n+z} = \overline{Y3 \ (X3 + Y2) \ (X3 + X2 + Y1) \ (X3 + X2 + X1 + Y0)} \\ \overline{C}_{n+z} = \overline{Y3 \ (X3 + Y2) \ (X3 + X2 + Y1) \ (X3 + X2 + X1 + Y0)} \\ \overline{C}_{n+z} = \overline{Y0 \ (X0 + C_{n})} \\ \overline{C}_{n+z} = \overline{Y0 \ (X0 + C_{n}$$

FUNCTION TABLE FOR G OUTPUT

		OUTPUT					
G3	G2	Ğ1	G0	P3	Ğ		
L	Х	Х	Х	X	X	X	L
X	L	X	X	L	X	X	L
X	X	L	X	L	L	X	L
×	X	X	L	L	L	L	L
	All	othe	r comi	binat	ions		н

FUNCTION TABLE FOR P OUTPUT

	INP	UTS		OUTPUT			
P3	P2	Ē1	ΡO	P			
L	L,	L	L	L			
	All d	other	•	Н			
C	mbi	natio	ons	''			

FUNCTION TABLE FOR C_{n+x} OUTPUT

#	NPUT	S	OUTPUT
Ğ0	P ₀	C _{n+x}	
L	Х	Н	
х	L	н	
	ll othe binati		L

FUNCTION TABLE FOR C_{n+y} OUTPUT

	iN	PUT		OUTPUT	
G1	G0	Cn	C _{n+y}		
L	Х	Х	X	Х	Н
X	L	L	Х	X	н
x	Х	L	L	Н	н
	ΑI	L			
	comi	oinat	ions		_

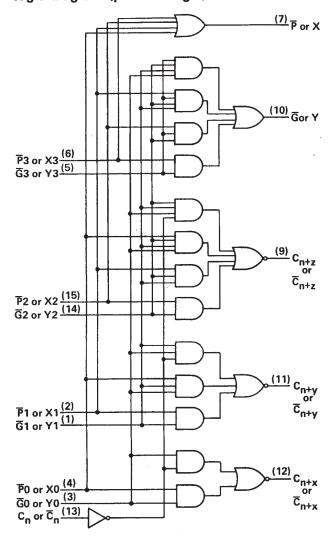
FUNCTION TABLE FOR Cn+z OUTPUT

		11	NPUT	S			OUTPUT
Ğ2	Ğ1	Cn	C _{n+z}				
L	Х	Х	Х	Х	Х	X	Н
Х	L	X	L	X	X	Х	н
X	X	L	L	L	X	X	н
х	X	Х	L	L	L	Н	н
	All	other	comi	oinati	ons		L

H = high level, L = low level, X = irrelevant

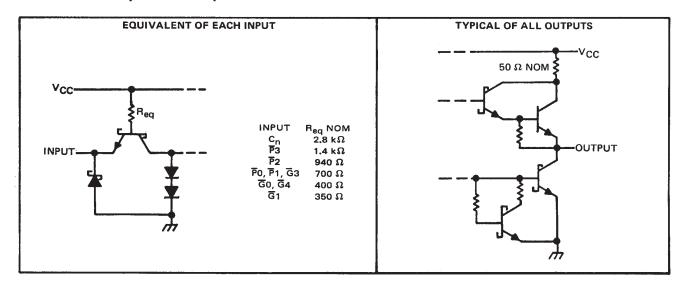
Any inputs not shown in a given table are irrelevant with respect to that output.

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7	7 V
Input voltage		
Interemitter voltage (see Note 2)	5.5	5 V
Operating free-air temperature range: SN54S182 – 55°C	to 125	°C
SN74S182 0°	'C to 70	°C
Storage temperature range65°C	to 150	°C

NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.

2. This is the voltage between two emitters of a multiple-emitter input transistor. For these circuits, this rating applies to each \overline{G} input in conjunction with any other \overline{G} input or in conjunction with any \overline{P} input.

recommended operating conditions

	S	SN54S182			SN74S182		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-1			-1	mA
Low-level output current, IOL			20			20	mA
Operating free-air temperature, TA	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAME	TED	TEST CO	NDITIONS†	S	N54S18	32	S	N74S18	2	UNIT
	PANAME	IEN	I EST CO	MDITIONS.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage	je			2			2	•		V
ViL	Low-level input voltage	je					0.8			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I _I = -18 mA			-1.2			-1.2	V	
VOH	High-level output volt	age	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OH} = -1 mA	2.5	3.4		2.7	3.4		٧
VOL	Low-level output volt	age	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OL} = 20 mA			0.5			0.5	٧
11	Input current at maxi	mum input voltage	V _{CC} = MAX,	V _I = 5.5 V			1			1	mA
	High-level	C _n input					50			50	
		P3 input]				100			100	
1		P2 input	VasaMAY	, V ₁ = 2.7 V			150			150	
ΉН	input current	PO, P1, or G3 input	CC - MAA,				200			200	μΑ
		G0 or G2 input					350			350	
		G1 input					400			400]
		C _n input					-2			-2	
		P3 input	1				-4			-4	
1	Low-level	P2 input],,,,,,,,,,	V: - 0 E V			6			6]^
ΙįΣ	input current	PO, P1, or G3 input	V _{CC} = MAX,	V ~ 0.5 V			-8			-8	mA
	•	GO or G2 input]				-14			-14	1
	G1 input					-16			-16		
IOS Short-circuit output current§		V _{CC} = MAX		-40		-100	-40		-100	mA	
Іссн	ICCH Supply current, all outputs high			See Note 3		35	65		35	70	mA
CCL	Supply current, all ou	tputs low	V _{CC} = MAX,	See Note 4		69	99		69	109	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
tPLH	Go, G1, G2, G3,	C _{n+x} , C _{n+y} ,			4.5	7	ns	
tPHL	P0, P1, P2, or P3	or C _{n+z}	1		4.5	7] ""	
tPLH	G0, G1, G2, G3,	G	7		5	7.5	ns	
tPH L	P1, P2, or P3	. .	$R_L = 280 \Omega$, $C_L = 15 pF$,		7	10.5	113	
t₽LH	P0, P1, P2, or P3	ī Ģ	See Note 5		4.5	6.5	ns	
tPHL	10,11,12,0113	•			6.5	10	""	
^t PLH	- C _n	C _{n+x} , C _{n+y} , or C _{n+z}			6.5	10	ns	
tPHL.	on .	or C _{n+z}			7	10.5	113	

NOTE 5: Load circuits and voltage waveforms are shown in Section 1.



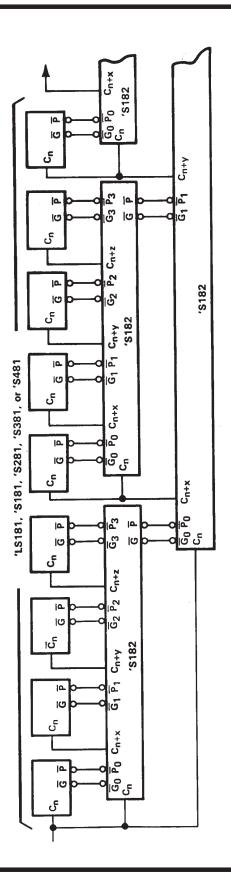
 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time and duration of the short-circuit test should not exceed one second.

NOTES: 3. ICCH is measured with all outputs open, inputs \$\overline{P}\$3 and \$\overline{G}\$3 at 4.5 V, and all other inputs grounded. MAX is determined at 5.5 V.

^{4.} ICCL is measured with all outputs open; inputs \$\overline{G0}\$, \$\overline{G1}\$, and \$\overline{G2}\$ at 4.5 V; and all other inputs grounded.

TYPICAL APPLICATION DATA



64-BIT ALU, FULL-CARRY LOOK-AHEAD IN THREE LEVELS

Remaining inputs and outputs of 'LS181, 'S181, 'S281, 'S381, and 'S481 are not shown.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07802BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07802BEA	Samples
M38510/07802BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07802BEA	Samples
SN54S182J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S182J	Samples
SNJ54S182FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 182FK	Samples
SNJ54S182J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S182J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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PACKAGE MATERIALS INFORMATION

www.ti.com 5-Jan-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SNJ54S182FK	FK	LCCC	20	1	506.98	12.06	2030	NA

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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